

7.0V to 9.5V

0.001% (Typ)

0.002% (Typ)

2.3Vrms(Typ)

-100dB(Typ)

-40°C to +85°C

38mA (Typ)

## Sound Processor with Built-in 3-band Equalizer **BD37544FS**

#### **General Description**

BD37544FS is a sound processor with built-in 3-band equalizer for car audio. The functions are stereo input selector (which can switch single and GND isolation), input-gain control, main volume, super bass, 5ch fader volume, LPF/HPF for subwoofer, and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and can construct a high quality car audio system.

#### **Features**

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, super bass, mixing by using advanced switch circuit.
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer, and HPF. It is possible to control Q, Gv, fo of 3-band equalizer and fc of LPF/HPF through I<sup>2</sup>C BUS control.
- It is possible to adjust the gain of the bass, middle, and treble up to ±20dB with 1 dB step gain adjustment.
- It is equipped with output terminals for Subwoofer. Moreover, the stereo signal output of the front and rear can also be chosen by the I<sup>2</sup>C BUS control.
- Built-in mixing input and mixing attenuator.
- Energy-saving design resulting in low-current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB lavout.
- It is possible to control the I<sup>2</sup>C BUS by 3.3V / 5V.

#### Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

#### **Key Specifications**

- Power Supply Voltage Range:
- Circuit Current (No Signal):
- Total Harmonic Distortion: THD+N1 THD+N2 Maximum Input Voltage:
- Cross-talk Between Selectors:
- Volume Control Range:
- +15 dB to -79dB Output Noise Voltage: V<sub>NO1</sub> 3.8µVrms(Typ)  $V_{NO2}$ 4.8µVrms(Typ) 1.8µVrms(Typ)
- **Residual Output Noise Voltage:**
- **Operating Temperature Range:**

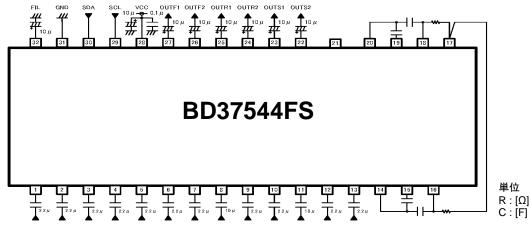
#### Package

W(Typ) x D(Typ) x H(Max)

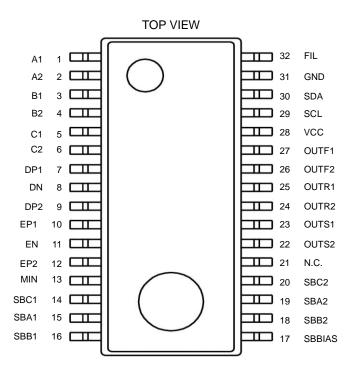


OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

## **Typical Application Circuit**



## **Pin Configuration**



## **Pin Descriptions**

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	17	SBBIAS	SuperBass bias terminal
2	A2	A input terminal of 2ch	18	SBB2	SuperBass setting terminal of 2ch
3	B1	B input terminal of 1ch	19	SBA2	SuperBass setting terminal of 2ch
4	B2	B input terminal of 2ch	20	SBC2	SuperBass setting terminal of 2ch
5	C1	C input terminal of 1ch	21	N.C.	No connection
6	C2	C input terminal of 2ch	22	OUTS2	Subwoofer output terminal of 2ch
7	DP1	D positive input terminal of 1ch	23	OUTS1	Subwoofer output terminal of 1ch
8	DN	D negative input terminal	24	OUTR2	Rear output terminal of 2ch
9	DP2	D positive input terminal of 2ch	25	OUTR1	Rear output terminal of 1ch
10	EP1	E positive input terminal of 1ch	26	OUTF2	Front output terminal of 2ch
11	EN	E negative input terminal	27	OUTF1	Front output terminal of 1ch
12	EP2	E positive input terminal of 2ch	28	VCC	Power supply terminal
13	MIN	Mixing input terminal	29	SCL	I <sup>2</sup> C Communication clock terminal
14	SBC1	SuperBass setting terminal of 1ch	30	SDA	I <sup>2</sup> C Communication data terminal
15	SBA1	SuperBass setting terminal of 1ch	31	GND	GND terminal
16	SBB1	SuperBass setting terminal of 1ch	32	FIL	VCC/2 terminal

## **Block Diagram**

32 31 30 29 28	27 26	25 24	23 22	21	20 19	18 17
VCC/2 GND I2C BUS LOGIC						
■ Fader Gain:+15dB to -79dB/1dB step				የ		
<mark>★no pop noise</mark> ■LPF				]		
fc=55/85/120/160Hz ■HPF						
■ hPF fc=55/85/120/160Hz ■ ATT	Fader★	Fader★	Fader	ATT ★		
Gain: +7dB to -79dB/1dB step						
<mark>★no pop noise</mark> ■Super Bass	$\sqrt{9}$		_∽ ∕`			
■ Super bass			LPF			
■3 Band P-EQ (Tone control)		HPF	L de la constante de la consta			
Gain: +20dB to -20dB/1dB step			•⊕•			
★no pop noise •Bass:f0=60/80/100/120Hz	-					
Q=0.5/1.0/1.5/2.0						
•Meddle:f0=500/1k/1.5k/2.5kHz		★Super Bass				
Q=0.75/1/1.25/1.5						
<ul> <li>Treble:f0=7.5k/10k/12.5k/15kHz</li> <li>Q=0.75/1.25</li> </ul>						
■Volume		★3 Band P-EQ (Tone control)				
Gain: +15dB to -79dB/1dB step		(Tone control)				
<b>★no pop noise</b> ■Input Gain	Г	★Volume/Mute				
Gain: +20dB to -0dB/1dB step						
★no pop noise	Г					
		★Input Gain				
Input selector	(3 single-end a	nd 2 stereo ISO)				
	Buffe	erdGND BufferdGND	BufferdGND B	ufferdGND		
	ISC	ISO amp	ISO amp	ISO amp		
	┉ᠵ┝┉ᠵ┝	┉┍┝┉┍┝┉	┍ᠵ╞╾┉ᠵᠵ╞╴┉	┍⊳┝┉┍	† †	t
1 2 3 4 5	6 7	8 9	10 11	12 13	14 15	16
						_

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0	V
Input Voltage	V <sub>IN</sub>	V <sub>cc</sub> +0.3 to GND-0.3	V
Power Dissipation	Pd	0.95 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on the standard board (70 x 70 x 1.6 mm<sup>3</sup>), derate by 7.6mW/°C for Ta above 25°C. Thermal resistance θja = 131.6(°C/W) Material : A FR4 grass epoxy board(3% or less of copper foil area) **Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated with the table table. over the absolute maximum ratings.

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	Vcc	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

## **Electrical Characteristics**

(Unless specified, Ta=25°C, V<sub>CC</sub>=8.5V, f=1kHz, V<sub>IN</sub>=1Vrms, Rg=600Ω, RL=10kΩ, A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, HPF OFF, Mixing OFF, Fader 0dB)

BLOCK	Parameter	Symbol		Limit		Unit	Conditions	
BLC	Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
	Circuit Current (No Signal)	la	-	38	48	mA	No signal	
	Voltage Gain	Gv	-1.5	0	+1.5	dB	G <sub>V</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
	Channel Balance	СВ	-1.5	0	+1.5	dB	$CB = G_{V1}-G_{V2}$	
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz	
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz	
GENERAL	Output Noise Voltage 1 (FRONT,REAR) *	V <sub>NO1</sub>	-	3.8	15	µVrms	Rg = 0Ω BW = IHF-A	
GENI	Output Noise Voltage 2 (SUBWOOFER) *	$V_{NO2}$	-	4.8	15	µVrms	Rg = 0Ω BW = IHF-A	
	Residual Output Noise Voltage*	V <sub>NOR</sub>	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A	
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	$\label{eq:rescaled} \begin{array}{l} Rg = 0\Omega \\ CTC = 20 log(V_OUT/V_IN) \\ BW = IHF-A \end{array}$	
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V <sub>RR</sub> =100mVrms RR=20log(Vcc IN/Vout)	
	Input Impedance(A, B,C)	R <sub>IN_s</sub>	70	100	130	kΩ		
~	Input Impedance(D, E)	R <sub>IN_D</sub>	175	250	325	kΩ		
SELECTOR	Maximum Input Voltage	V <sub>IM</sub>	2.1	2.3	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz	
	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	$\begin{array}{l} Rg = 0\Omega \\ CTS = 20 log(V_OUT/V_IN) \\ BW = IHF-A \end{array}$	
INPUT	Common Mode Rejection Ratio*	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V <sub>IN</sub> /V <sub>OUT</sub> ) BW = IHF-A,[*X…D,E]	

## **Electrical Characteristics - continued**

				Limit						
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions			
GAIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )			
	Maximum Input Gain	Gin_max	18	20	22	dB	Input gain 20dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )			
	Gain Set Error	Gin_err	-2	0	+2	dB	GAIN=+20dB to +1dB			
MUTE	Mute Attenuation *	Gmute	-	-105	-85	dB	Mute ON G <sub>MUTE</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A			
	Maximum Gain	G <sub>V_MAX</sub>	13	15	17	dB	Volume = $15dB$ V <sub>IN</sub> =100mVrms G <sub>V</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )			
VOLUME	Maximum Attenuation *	Gv_min	-	-100	-85	dB	$      Volume = -∞dB        G_V=20log(V V_{OUT}/V_{IN})        BW = IHF-A $			
Ŋ	Attenuation Set Error 1	$G_{V\_ERR1}$	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB			
	Attenuation Set Error 2	$G_{V\_ERR2}$	-3	0	+3	dB	ATT=-16dB to -47dB			
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB			
	Maximum Boost Gain	G <sub>B_BST</sub>	18	20	22	dB	Gain=+20dB f=100Hz V <sub>IN</sub> =100mVrms G <sub>B</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
BASS	Maximum Cut Gain	Gb_cut	-22	-20	-18	dB	Gain=-20dB f=100Hz V <sub>IN</sub> =2Vrms G <sub>B</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
	Gain Set Error	Gb_err	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz			
щ	Maximum Boost Gain	G <sub>M_BST</sub>	18	20	22	dB	Gain=+20dB f=1kHz V <sub>IN</sub> =100mVrms G <sub>M</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
MIDDLE	Maximum Cut Gain	<b>G</b> м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V <sub>IN</sub> =2Vrms G <sub>M</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
	Gain Set Error	Gm_err	-2	0	+2	dB	Gain=-20dB to +20dB f=1kHz			
ш	Maximum Boost Gain	G <sub>T_BST</sub>	18	20	22	dB	Gain=+20dB f=10kHz V <sub>IN</sub> =100mVrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
TREBLE	Maximum Cut Gain	Gt_cut	-22	-20	-18	dB	Gain=-20dB f=10kHz V <sub>IN</sub> =2Vrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )			
	Gain Set Error	$G_{T\_ERR}$	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz			
	Input Impedance	RIN_M	19	27	35	kΩ				
Ŭ	Maximum Input Voltage	VIM_M	2.0	2.2	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz			
MIXING	Maximum Attenuation *	Gmx_min	-	-100	-85	dB	MIX=OFF G <sub>MX</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW=INF-A			
	Maximum Gain	Gмх_мах	5	7	9	dB	ATT=+7dB G <sub>MX</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )			

## **Electrical Characteristics - continued**

BLOCK	Parameter	Symbol	Limit			Unit	Conditions	
BLC	Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
	Maximum Boost Gain	G <sub>F_BST</sub>	13	15	17	dB	Fader=15dB V <sub>IN</sub> =100mVrms G <sub>F</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
SUBWOOFER	Maximum Attenuation *	GF_MIN	-	-100	-90	dB	Fader = -∞dB G <sub>F</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A	
BWG	Gain Set Error	Gf_err	-2	0	+2	dB	GAIN=+1dB to +15dB	
/ SU	Attenuation Set Error 1	GF_err1	-2	0	+2	dB	ATT=-1dB to -15dB	
FADER	Attenuation Set Error 2	Gf_err2	-3	0	+3	dB	ATT=-16dB to -47dB	
FAD	Attenuation Set Error 3	G <sub>F_ERR3</sub>	-4	0	+4	dB	ATT=-48dB to -79dB	
	Output Impedance	Rout	-	-	50	Ω	V <sub>IN</sub> =100mVms	
	Maximum Output Voltage	V <sub>ом</sub>	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz	

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for \* measurement. Phase between input / output is same.

## **Typical Performance Curves**

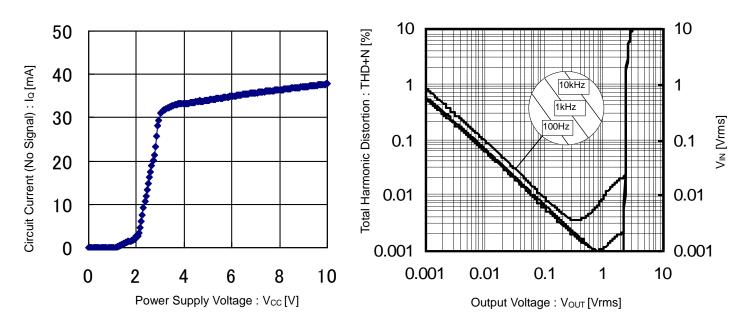


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

Figure 2. Total Harmonic Distortion vs Output Voltage

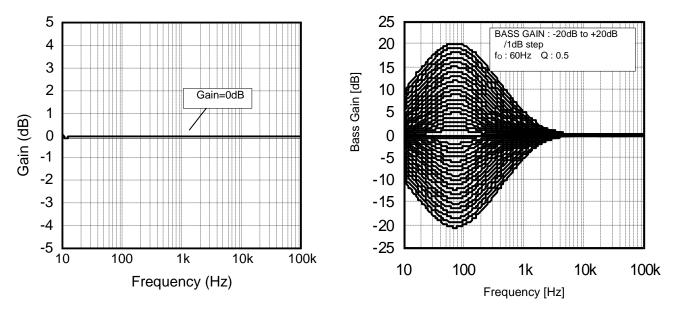


Figure 3. Gain vs Frequency

Figure 4. Bass Gain vs Frequency

## **Typical Performance Curves – continued**

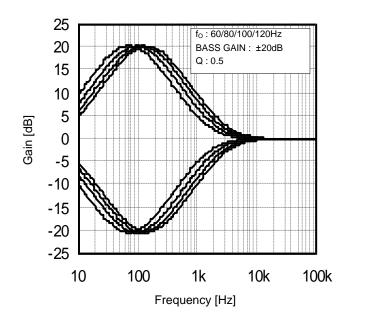
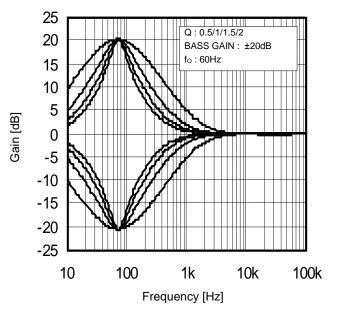
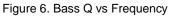


Figure 5. Bass fo vs Frequency





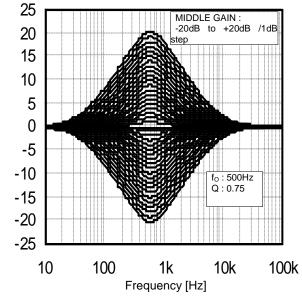


Figure 7. Middle Gain vs Frequency

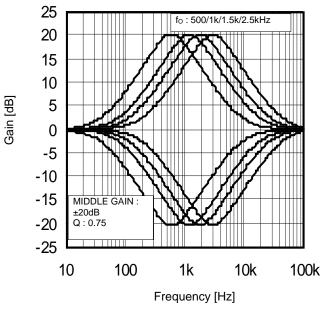
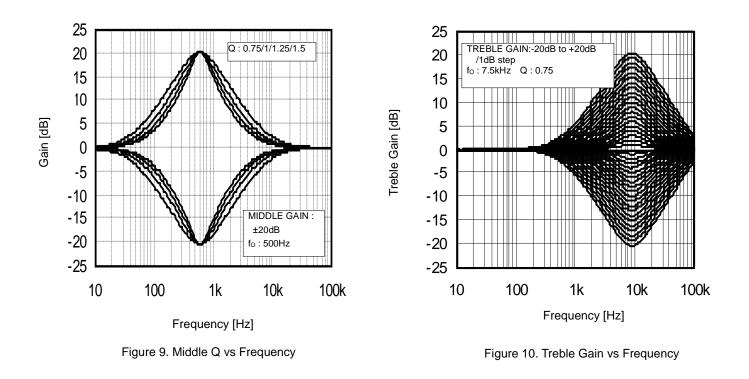


Figure 8. Middle fo vs Frequency

Middle Gain [dB]

## **Typical Performance Curves – continued**



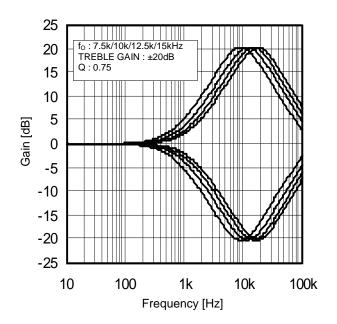


Figure 11. Treble fo vs Frequency

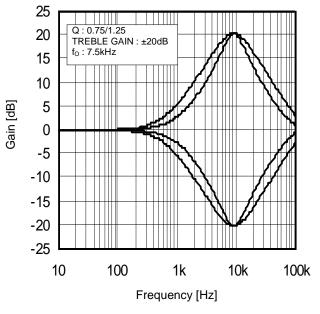


Figure 12. Treble Q vs Frequency

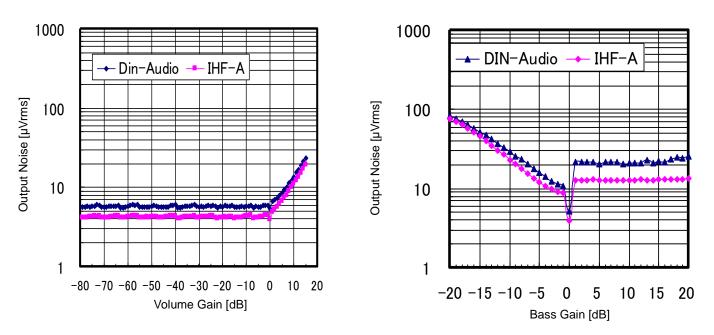
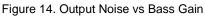


Figure 13. Output Noise vs Volume Gain

Figure 15. Output Noise vs Middle Gain



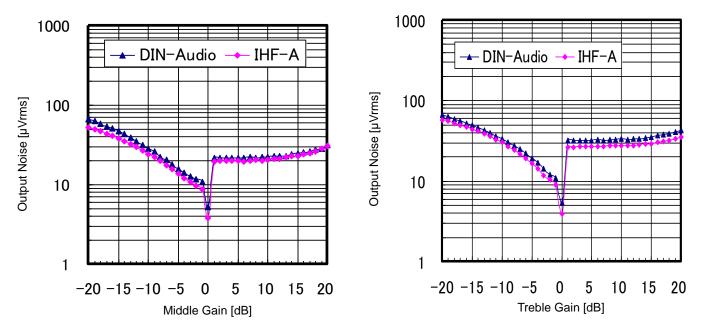


Figure 16. Output Noise vs Treble Gain

## **Typical Performance Curves – continued**

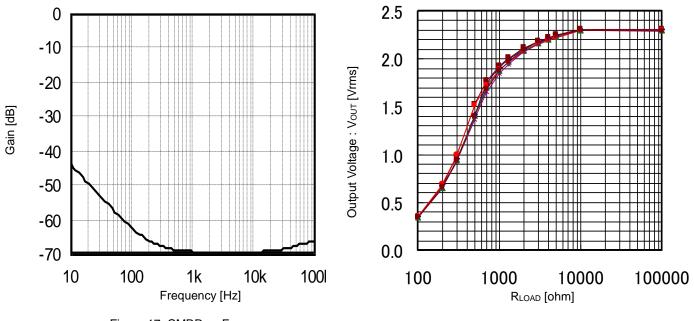
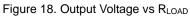


Figure 17. CMRR vs Frequency



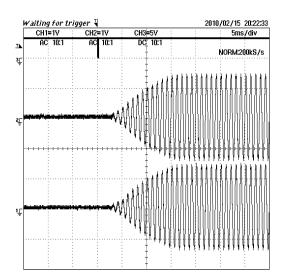


Figure 19. Advanced Switch 1

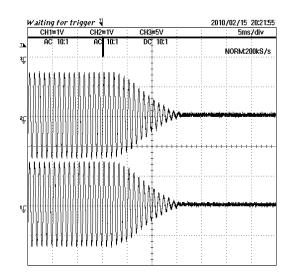


Figure 20. Advanced Switch 2

## Timing Chart CONTROL SIGNAL SPECIFICATION

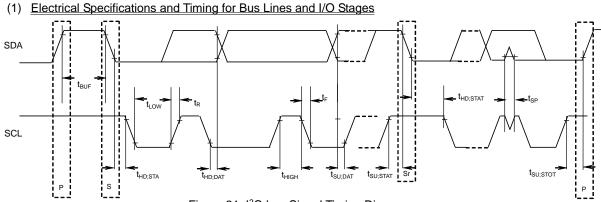


Figure 21. I<sup>2</sup>C-bus Signal Timing Diagram

Table 1	Characteristics of the	e SDA and SCL bus	lines for I <sup>2</sup> C-bus	devices (Ta=25	°C, V <sub>CC</sub> =8.5V)
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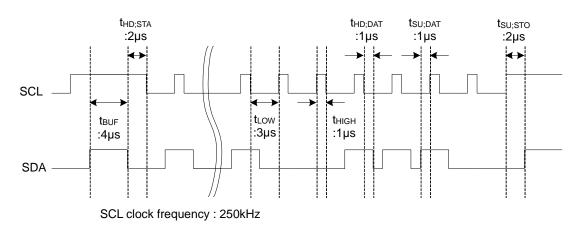
	Parameter	Symbol	Fast-mode	Unit		
	Falalletel	Symbol	Min	Max	Offic	
1	SCL clock frequency	fscL	0	400	kHz	
2	Bus free time between a STOP and START condition	<b>t</b> BUF	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	<b>t</b>	0.6			
3	pulse is generated	thd;sta	0.6	-	μS	
4	LOW period of the SCL clock	tLOW	1.3	-	μS	
5	HIGH period of the SCL clock	tнigн	0.6	-	μS	
6	Set-up time for a repeated START condition	t <sub>SU;STA</sub>	0.6	-	μS	
7	Data hold time:	thd;dat	0.06 (Note)	-	μS	
8	Data set-up time	tsu;dat	120	-	ns	
9	Set-up time for STOP condition	t <sub>su;sтo</sub>	0.6	-	μS	

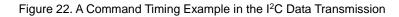
All values refer to VIH Min and VIL Max Levels (see Table 2).

(Note) A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL. For 7(tHD;DAT), 8(tsu;DAT), make the setup in which the margin is full.

#### Table 2 Characteristics of the SDA and SCL I/O stages for I<sup>2</sup>C-bus devices

	Parameter	Symbol	Fast-mode	Unit	
	Falamelei	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	Vін	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t <sub>SP</sub>	0	50	ns
13	LOW level output voltage: at 3mA sink current	Vol1	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	h	-10	+10	μA





## (2) <u>I<sup>2</sup>C BUS FORMAT</u>

	MSB LSB	MSB	LSB	MSB	LSB			
S	Slave Address	A Select	Address A	Data	А	Р		
1bit	8bit	1bit	8bit 1bit	8bit	1bit	1bit		
	S = Start condition (Recognition of start bit)							
	Slave Address = Recognition of slave address. The first 7 bits correspond to the slave address.							
	The least significant bit is "L" which corresponds to write mode.							
	А	= ACKNOWLED	OGE bit (Recogni	tion of acknowled	gement)			
	Select Address	= Select addres	s corresponding	to volume, bass c	or treble.			
	Data = Data on every volume and tone.							
	Р	= Stop condition	(Recognition of	stop bit)				

## (3) <u>I<sup>2</sup>C BUS Interface Protocol</u>

(;	(a) Basic Format										
	S	Slave Addre	ess	А	Select A	ddress	А	Da	ta	Α	Ρ
		MSB	LSB		MSB	LSB	N	/ISB	LSE	3	

(b) Automatic Increment (Select Address increases (+1) according to the number of data.)

S		Slave Address	А	Select Address	А	Data1	А	Data2	А		DataN	А	Ρ
	Ν	MSB LSI	3	MSB LS	В	MSB LS	В	MSB	LS	В	MSB	LS	В
(Ex	an	nple)											

Data1 shall be set as data of address specified by Select Address.
 Data2 shall be set as data of address specified by Select Address +1.

③ DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

 S
 Slave Address
 A
 Select Address1
 A
 Data
 A
 Select Address1
 Select Address1
 A
 Select Address1
 A
 Select Address1
 Select Address1

S	SI	ave Address	Α	Select Add	ress1	А	Dat	а	А	Select	Addres	ss 2	А	Dat	a	Α	Ρ
Ν	/ISB	LS	В	MSB	LSB		MSB	LS	βB	MSB		LSB	Ν	ISB	LS	В	
		(Note) If any data is transmitted as Select Address 2 next to data, it is recognized															
		as d	ata,	not as Select	Addres	ss 2	<u>2</u> .										

#### (4) Slave Address

Ν	<b>MSB</b>							LSB	
	A6	A5	A4	A3	A2	A1	A0	R/W	
	1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Items	Select Address	MSB			Da	ata			LSB		
nems	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advanced switch ON/OFF	0	Input Gai	witch time of n/Volume /Super Bass ting	0	1	1 Advanced sw of Mu			
Initial setup 2	02	LPF Phase	0		er Output lect	0	Su	Ibwoofer LP	F f <sub>C</sub>		
Initial setup 3	03	Front HPF Pass	Rear HPF Pass	Fro	nt / Rear HP	ar HPF f <sub>C</sub> 0 1 0					
Input Selector	05	Full-diff Type	0	0			Input selecto	selector			
Input gain	06	Mute ON/OFF	0	0			Input Gain				
Volume gain	20		-	١	olume Gain	/ Attenuatio	on				
Fader 1ch Front	28		Fader Gain / Attenuation								
Fader 2ch Front	29		Fader Gain / Attenuation								
Fader 1ch Rear	2A				Fader Gain	/ Attenuatio	n				
Fader 2ch Rear	2B				Fader Gain	/ Attenuatio	n				
Fader Subwoofer	2C				Fader Gain	/ Attenuatio	n				
Mixing	30				Mixing Gain	/ Attenuatio	n				
Bass setup	41	0	0	Bas	s f <sub>o</sub>	0	0	Bas	ss Q		
Middle setup	44	0	0	Mido	lle fo	0	0	Mide	dle Q		
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q		
Bass gain	51	Bass Boost/ Cut	0	0	Bass Gain						
Middle gain	54	Middle Boost/ Cut	0	0	0 Middle Gain						
Treble gain	57	Treble Boost/ Cut	0	0			Treble Gain				
Super Bass Gain	75	0	0	0		Si	uper Bass G	ain			
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

#### Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$\rightarrow 01 \rightarrow 02 \rightarrow 03 \rightarrow 05 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C$$

$$\rightarrow 30 \rightarrow 41 \rightarrow 44 \rightarrow 47 \rightarrow 51 \rightarrow 54 \rightarrow 57 \rightarrow 75$$

- 3. Advanced switch is not used for the function of input selector and subwoofer output select, etc. Therefore, please apply mute on the side when changing these settings.
- 4. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF for waiting advanced-mute time.

|--|

Time	MSB	MSB Advanced switch time of Mute LSI										
TIIIIC	D7	D6	D5	D4	D3	D2	D1	D0				
0.6msec	Advonced		Advanced	switch time			0	0				
1.0msec	Advanced Switch	0	of Input ga	ain/Volume	0	1	0	1				
1.4msec	ON/OFF	0		ler/Super	0	1	1	0				
3.2msec			Bass/Mixing				1	1				

Time	MSB	Advanced switch time of Input MSB gain/Volume/Tone/Fader/ LSB Super Bass/Mixing										
	D7	D6	D5	D4	D3	D2	D1	D0				
4.7 msec	Advonced		0	0	0							
7.1 msec	Advanced Switch	0	0	1		1	Advanc	ed switch				
11.2 msec	ON/OFF	0	1	0	U	I	Time	of Mute				
14.4 msec			1	1								

Mode	MSB	MSB Advanced switch ON/OFF									
Mode	D7	D6	D5	D4	D3	D2	D1	D0			
OFF	0	0	Advanced switch time of Input gain/Volume		0	1		ed switch			
ON	1	Ū		der/Super Mixing	Ū	-	Time o	of Mute			

Select address 02(hex)

fa	MSB Subwoofer LPF fc							LSB	
fc	D7	D6	D5	D4	D3	D2	D1	D0	
OFF						0	0	0	
55Hz						0	0	1	
85Hz	LPF	0	Subwoofer Output		0	0	1	0	
120Hz	Phase	0	Se	Select	0	0	1	1	
160Hz						1	0	0	
Prohibition						Other setting			

Mode	MSB	:	Subwo	oofer (	Dutput	Selec	ct	LSB		
	D7	D1	D0							
LPF		0	0	0						
Front	LPF		0	1		-	- (			
Rear	Phase		1	0	0	Subwoofer LPF fc				
Prohibition			1	1						

Phase	MSB			LPF Phase						
Fliase	D7	D6	D5	D4	D3	D2	D1	D0		
0°	0	0	Subwoofer output select		0	Subwoofer I		= fo		
180°	1	0			0	Subwoofer LPF fc				

Select address 03(hex)

Mode	MSB	MSB Front/Rear HPF fc										
Mode	D7	D6	D5	D4	D3	D2	D1	D0				
55Hz			0	0	0							
85Hz	Front	Rear HPF Pass	0	0	1							
120Hz	HPF		1	1	0	0	1	0				
160Hz	Pass		Pass	0	1	0						
Prohibition			(	Other setting	9							

Mode	MSB		Rear HPF						
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
pass	Front	0	<b>F</b> <sub>1</sub>		<b>-</b> 4	0		0	
NOT pass	HPF Pass	1	Fro	ont/Rear HPI	FIC	0	1	0	

Mode	MSB			Front HPF				
Mode	D7	D6	D5	D4	D3	D2	D1	D0
pass	0	Rear	Г		- 4	0	4	0
NOT pass	1	HPF Pass	Fro	ont/Rear HPI		0		U

#### Select address 05(hex)

Mode			MSB		In	put S	electo	or		LSB			
wode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0			
Α	A1	A2				0	0	0	0	0			
В	B1	B2				0	0	0	0	1			
С	C1	C2				0	0	0	1	0			
D single	DP1	DP2	<b>E</b>			0	0	0	1	1			
E single	EP1	EP2	Full-			0	0	1	0	0			
A diff	A1	B1	diff bias	0	0	0	1	1	1	1			
C diff	B2	C2	type select			1	0	0	0	0			
D diff	DP1	DP2	361601				0	0	1	1	0		
E diff	EP1	EP2							0	0	1	1	1
Inp	out SHOR	RΤ.				0	1	0	0	1			
P	Prohibitior	1					C	ther setting	g				

**Input SHORT** : The input impedance of each input terminal is lowered from  $100k\Omega(Typ)$  to  $6 k\Omega(Typ)$ . (For quick charge of coupling capacitor)

## **BD37544FS**

D7     D6     D5     D4     D3     D2     D1     D0       Negative Input     0     0     0     Input Selector       Negative input type     1ch tch signal input     1ch tch signal input     1ch tch signal input     1ch tch signal input       Bias type     For differential amplifier type     1ch tch signal input     1ch tch signal input     1ch tch signal input	Mode	MSB	F	Full-dif	f Bias	Туре	Select	t	LSB
Bias     1     0     0     Imput Selector       Negative input type     Ich     Ich     Ich     Ich       For Ground –isolation type.     Ich     Ich     Ich     Ich       Bias type     Ich     Ich     Ich     Ich       Bias type     For differential amplifier type     Ich     Ich     Ich       Ich     Ich     Ich	wode	D7	D6	D5	D4	D3	D2	D1	D0
Bias       I         Negative input type       1ch         For Ground –isolation type.       1ch         Bias type       2ch         For differential amplifier type       1ch         1ch       1ch         1ch<			0	0			nnut Selecto	r	
Negative input type       1ch         For Ground –isolation type.       1ch         Bias type       2ch         For differential amplifier type       1ch         1ch	Bias	1	Ŭ	Ŭ		1		•	
Bias type For differential amplifier type $1ch_{1ch signal input}$		-			ut	, <b>▶</b> _ <u> </u> ]+	10		ial
Bias type       For differential amplifier type       1ch 1ch signal input	For Ground –isol	ation type.				<u></u> +		Different	iai
2ch     2ch       2ch signal input     ++       Bias type       For differential amplifier type       1ch       <						П			
2ch     2ch     Differential       2ch signal input     1ch     1ch       1ch signal input     1ch     1ch       1ch the signal input     1ch     1ch       1ch the signal input     1ch     1ch						┥── <sup>╏+</sup>		2ch	
Bias type For differential amplifier type 1ch 1ch signal input 1ch = + 10 1ch					_	<del>//</del>	EP2		ial
For differential amplifier type 1ch 1ch signal input 1ch 1ch signal input 1ch 1ch 1ch 1ch 1ch 1ch 1ch 1ch				2ch signal inp		, ▶─∄⁺─	13		
For differential amplifier type 1ch 1ch signal input 1ch 1ch signal input 1ch 1ch 1ch 1ch 1ch 1ch 1ch 1ch	Bias type				Ũ		EP1		
$\begin{array}{c} 1 \text{ Cn} \\ 1 \text{ ch signal input} \end{array}$	For differential an	nplifier type				▶+	10	1ch	
EN2 + 12 2ch					$\sim$		EN1		tial
₩ 12						▶−∄⁺−	·[11]L		
						⊾ и+	EN2		
2ch EP2   Differential							12		
			2ch			ЕР2 ► H+ Ца		Different	tial

## Select address 06 (hex)

Gain	MSB			Inpu	ıt Gair	<u>ו</u>		LSB	
Gain	D7	D6	D5	D4	D3	D2	D1	D0	
0dB				0	0	0	0	0	
1dB				0	0	0	0	1	
2dB				0	0	0	1	0	
3dB				0	0	0	1	1	
4dB				0	0	1	0	0	
5dB				0	0	1	0	1	
6dB				0	0	1	1	0	
7dB				0	0	1	1	1	
8dB				0	1	0	0	0	
9dB			0		0	1	0	0	1
10dB				0	1	0	1	0	
11dB	Mute	0		0	1	0	1	1	
12dB	ON/OFF	0		0	1	1	0	0	
13dB				0	1	1	0	1	
14dB				0	1	1	1	0	
15dB				0	1	1	1	1	
16dB				1	0	0	0	0	
17dB				1	0	0	0	1	
18dB				1	0	0	1	0	
19dB				1	0	0	1	1	
20dB				1	0	1	0	0	
				1	1	0	1	1	
Prohibition				:	:	:	:	:	
				1	1	1	1	1	

: Initial condition

Г

Select address 06 (hex)

Mode	MSB		l∨	lute O		LSB			
Widde	D7	D6	D5	D4 D3 D2 D1				D0	
OFF	0	0	0			Innut Coin			
ON	1	0	0 0 Input Gain						

## Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	I, Fad	er Gai	n / Att	enuati	ion	LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

## Select address 30(hex)

Gain & ATT	MSB	Г	Mixing	Gain	/ Atter	nuation	า	LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

(Note) See the precaution on P30 together, too.

#### Select address 41(hex)

Q factor	MSB	MSB		Bass Q factor				LSB
QTACION	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0		Por	a f	0	0	0	1
1.5	0	0	Das	ss f <sub>o</sub>	0	0	1	0
2.0							1	1

fa	MSB			Bass f <sub>o</sub>					
10	D7	D6	D5	D4	D3	D2	D1	D0	
60Hz			0	0					
80Hz		0	0	1	0	0	Bass Q factor		
100Hz	0		1	0	0	0			
120Hz			1	1					

## Select address 44(hex)

Q factor	MSB		Mi	Middle		ctor		LSB
QTACION	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	0		Mida	Middle fo		0	0	1
1.25	U	U	IVIICO		0	0	1	0
1.5							1	1

fa	MSB		Middle fo L						
10	D7	D6	D5	D4	D3	D2	D1	D0	
500Hz			0	0			Middle Q factor		
1kHz	0	0	0	1	0				
1.5kHz	0	0	1	0	0	0			
2.5kHz			1	1					

## Select address 47 (hex)

Q factor	MSB		Т	reble	ctor		LSB	
QTACION	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Troh	lo fe	0	0	0	0
1.25	0	0	Trec	ole fo	0	0	0	1

fo	MSB			Treb	le fo			LSB
TO	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz		0	0	0	0	0	0	
10kHz	0		0	1				Treble
12.5kHz	U		1	0				Q factor
15kHz			1	1				

Caia	MSB		Bass/I	Middle	e/Treb	le Gaiı	n	LSE
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost	Ū.	Ū	0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
Tronibilion				1	1	1	1	0
				1	1	1	1	1

Mode	MSB	Ba	ss/Mic	ddle/Ti	reble E	300st/	Cut	LSB
woue	D7	D6	D5	D4	D3	D2	D1	D0
Boost	0	0	0		Beec/	/liddle/Trebl	a Cain	
Cut	1	0	0		Da55/1		e Gain	

Gain	MSB		Su	iper B	ass G	ain		LSE
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB		_	_	0	1	0	1	1
12dB	0	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

(Note) About Super Bass, the above Gain is for in indication purposes. Actual Gain (=20log (V<sub>OUT</sub>/V<sub>IN</sub>)) is different. Refer to P31 to P34 for the details.

: Initial condition

#### (6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn ON mute until this initial data is sent.

Parameter	Symbol		Limit		Unit	Conditions		
Falameter	Symbol	Min	Тур	Max	Unit	Conditions		
Rise Time of VCC	trise	33	-	-	µsec	$V_{CC}$ rise time from 0V to 5V		
VCC Voltage of Release Power ON Reset	Vpor	-	4.1	-	V			

## **Application Information**

## 1. Function and Specifications

Function and Specifica Function	Specifications							
	Stereo input							
	Single-End/Differential							
	(Possible to set the number of single-end/ differential as follows )							
Input selector	Single-End Differential							
	Mode 1         0         4           Mode 2         1         3							
	Mode 2         1         3           Mode 3         3         2							
	Mode 4 4 1							
	Mode 5 5 0 Table.1 Combination of input selector							
	+20dB to 0dB (1dB step)							
Input gain	Possible to use "Advanced switch" for prevention of switching noise.							
Mute	Possible to use "Advanced switch" for prevention of switching noise.							
Volume	· +15dB to -79dB (1dB step), -∞dB							
volume	Possible to use "Advanced switch" for prevention of switching noise.							
	· +20dB to -20dB (1dB step)							
Bass	• Q=0.5, 1, 1.5, 2							
Dass	• f <sub>0</sub> =60, 80, 100, 120Hz							
	Possible to use "Advanced switch" for prevention of switching noise.							
	+20dB to -20dB (1dB step)							
Middle	· Q=0.75, 1, 1.25, 1.5							
inidate	• fo=500, 1k, 1.5k 2.5kHz							
	Possible to use "Advanced switch" for prevention of switching noise.							
	+20dB to -20dB (1dB step)							
Treble	· Q=0.75, 1.25							
	• f <sub>0</sub> =7.5k, 10k, 12.5k, 15kHz							
	Possible to use "Advanced switch" for prevention of switching noise.							
Fader	<ul> <li>+15dB to -79dB(1dB step), -∞dB</li> </ul>							
	Possible to use "Advanced switch" for prevention of switching noise.							
LPF	• fc=55/85/120/160Hz, pass							
	Phase shift (0°/180°)							
HPF	• fc=55/85/120/160Hz, pass							
	Monaural input							
Mixing	<ul> <li>+7dBdB to -79dB (1dB step), -∞dB</li> </ul>							
	Possible to use "Advanced switch" for prevention of switching noise.							
Super Bass	+20dB to 0dB (1dB step)							
	Possible to use "Advanced switch" for prevention of switching noise.							

## 2. Volume / Fader Volume / Mixing ATT Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1

Adjustable range of mixing ATT is +7dB to -∞dB.

: Initial condition

## 3. Application Circuit

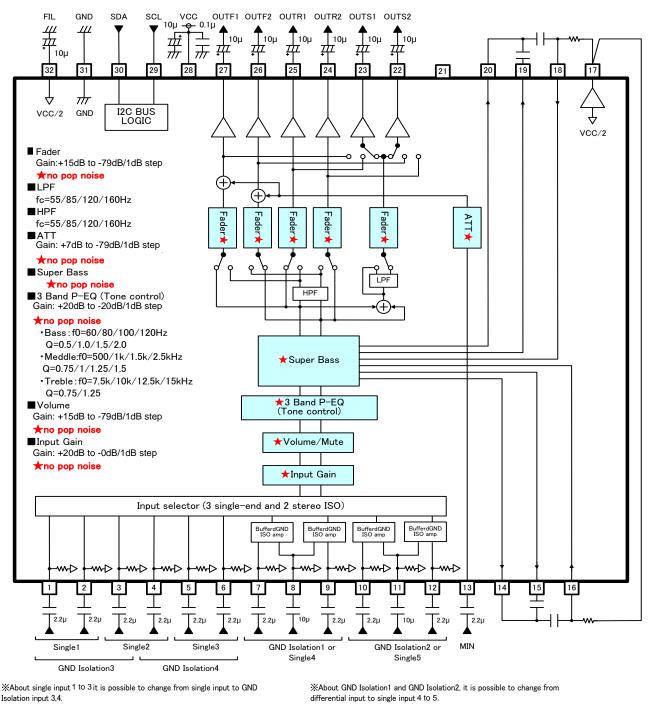


Figure 23. BD37544FS

#### Unit R : [Ω] C : [F]

#### Notes on wiring

①Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
 ②GND lines should be one-point connected.
 ③Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
 ④SCL and SDA lines of I<sup>2</sup>C BUS should not be parallel if possible.

The lines should be shielded, if they are adjacent to each other.

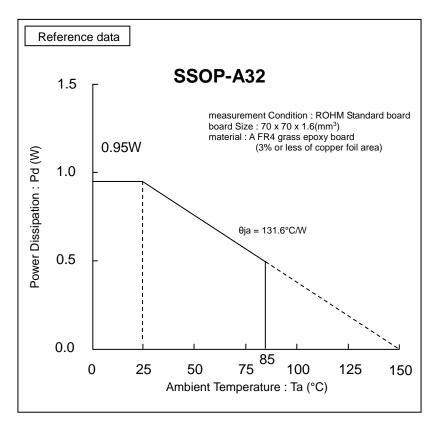
⑤Analog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent.

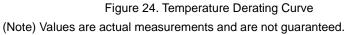
6 Please short Pins 15-16, and Pins 18-19 if the Super Bass is not used.

## **Power Dissipation**

About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.





Power dissipation values vary according to the board on which the IC is mounted.

## I/O Equivalent Circuits

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25		A terminal for signal input. The input impedance is 100kΩ(Typ).
7 8 9 10 11 12	DP1 DN DP2 EP1 EN EP2	4.25		Input terminal available to ingle/Differential mode. The input impedance is 250kΩ(Typ).
16 18	SBB1 SBB2	-		An input terminal for Super Bass
15 17 19 22 23 24 25 26 27	SBA1 SBBIAS SBA2 OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25		A terminal for Super Bass and fader, Subwoofer output.
14 20	SBC1 SBC2	4.25		An output terminal for Super Bass.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

## I/O Equivalent Circuits - continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
28	VCC	8.5		Power supply terminal.
29	SCL	-	VCC	A terminal for clock input of I <sup>2</sup> C BUS communication.
30	SDA	-	VCC	A terminal for data input of I <sup>2</sup> C BUS communication.
31	GND	0		Ground terminal.
32	FIL	4.25		1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
13	MIN	4.25		A terminal for signal input. The input impedance is 27kΩ(typ).

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

## **Operational Notes**

#### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

## 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

## 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

## 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

## 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

## 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

## 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

#### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

#### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

#### 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

#### 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

## **Operational Notes – continued**

#### 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

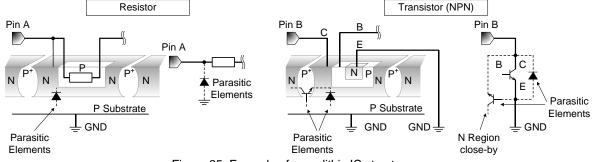
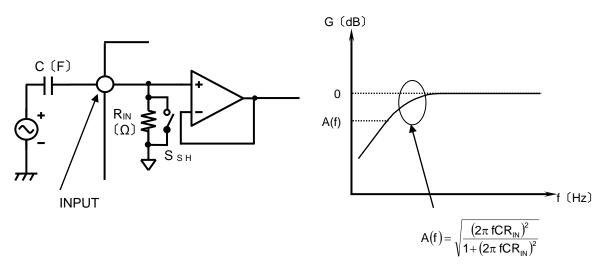


Figure 25. Example of monolithic IC structure

## 13. About Signal Input

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance  $R_{IN}(\Omega)$  at the input signal terminal of the IC. The first HPF characteristic of RC is composed.



#### (b) About the Input Selector SHORT

SHORT mode is the command which makes switch  $S_{SH}$  =ON of input selector part so that the input impedance  $R_{IN}$  of all terminals becomes small. Switch  $S_{SH}$  is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of  $S_{SH}$  and makes it low impedance, please use it at no signal condition.

## **Operational Notes – continued**

- 14. About MIX
  - (1) <u>About Specification of Fader -∞ at MIX ON.</u> Mix\_signal is added to Main\_signal after Fader\_Gain(+15dB to -79dB) like the figure. When Fader is set at -∞, the signal after a MIX signal is added is done with MUTE because the -∞ circuit of Fader is in the step after the addition circuit

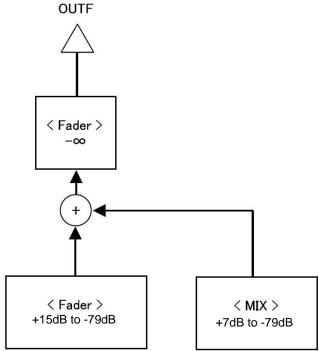
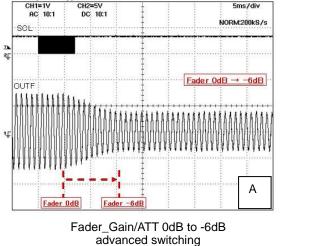
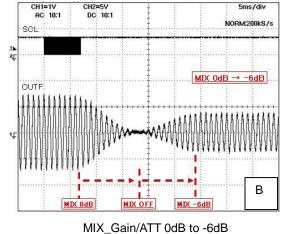


Figure 26. About Front Fader and MIX

(2) <u>About Advanced Switching of MIX\_Gain/ATT</u> When advanced switching of MIX\_Gain/ATT works, MIX goes a switching movement that it passes through the state of MIX\_OFF like in B figure below (from current settingof MIX\_Gain/ATT to MIX\_OFF to a target setting of MIX\_Gain/ATT).





MIX\_Gain/ATT 0dB to -6dI advanced switching

Figure 27. Advanced Switching Movement when MIX\_Gain/ATT is Changed

## **Operational Notes – continued**

#### 15. About Super Bass Circuit

The (the following Super Bass) which strengthens a low band like the graph below a can be realized by composing an external circuit with the pin 14 to 20 as shown in Figure 28.

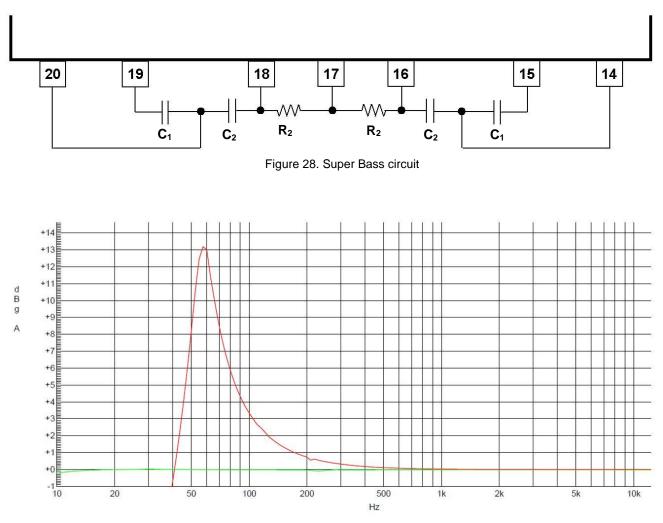
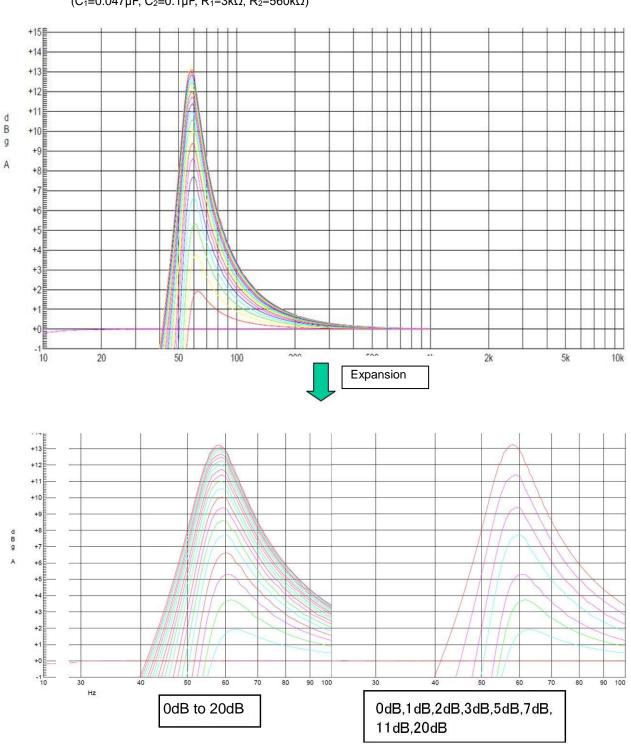


Figure 29. Super Bass Gain vs Frequency

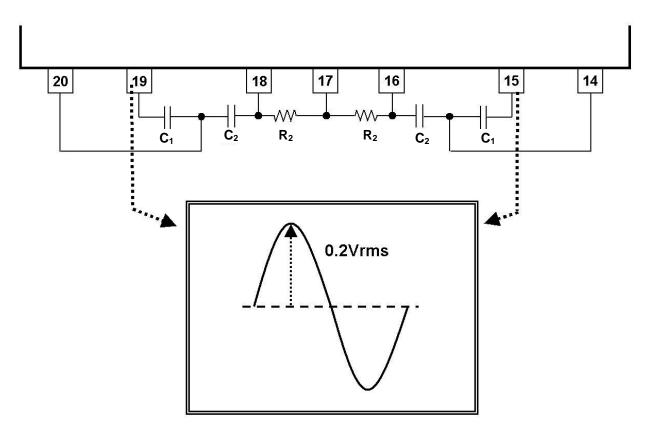


(a) <u>Gain Step Width becomes a Logarithm</u> When a setup of Gain is made 0,1,2,3,5,7,11,20dB, it becomes the following (bottom right) character.  $(C_1=0.047\mu$ F,  $C_2=0.1\mu$ F,  $R_1=3k\Omega$ ,  $R_2=560k\Omega$ )

Figure 30. About Gain step of Super Bass

(b) You must take level diagram into consideration so that output may not do a clip

<u>Example (C<sub>1</sub>=0.047µF, C<sub>2</sub>=0.1µF, R<sub>2</sub>=560kohm, V<sub>CC</sub>=8.5V)</u> To prevent output clipping due to amplification when Super Bass is used, adjust the level diagram with volume until the Tone output level becomes less than 0.2Vrms.



Please adjust so that the maximum level of the Tone output becomes less than 0.2Vrms. (at Vcc=8.5V)

Figure 31. Super Bass Level Diagram

## (c) About fo and Gain of Super Bass

fo and Gain of Super Bass deviates due to the deviation of the value of  $C_1$ ,  $C_2$ ,  $R_2$  (Components with the outside), D. (the resistance built is  $|O\rangle$ 

 $R_1$  (the resistance built in IC).

<u>Example</u> : Super Bass Gain – frequency characteristic at Dispersion condition of  $C_{1}$ ,  $C_{2}$ ,  $R_{2}$  ±5%,  $R_{1}$  ±30% ( $C_{1}$ =0.047 $\mu$ F,  $C_{2}$ =0.1 $\mu$ F,  $R_{1}$ =3kohm,  $R_{2}$ =560kohm, Super Bass Gain=20dB)

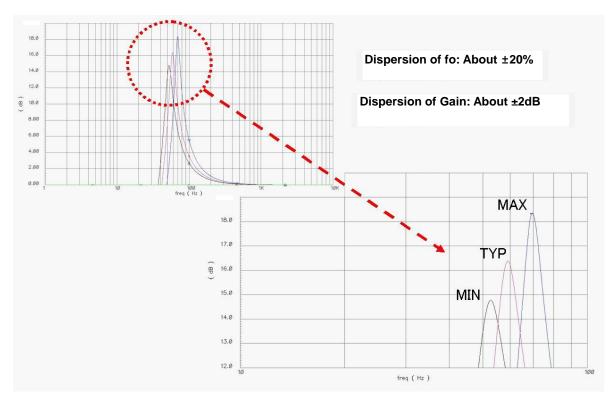
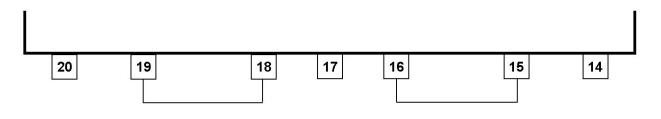


Figure 32. Dispersion of fo and Gain of Super Bass

## (d) How to Deal with Pins of Super Bass when not used

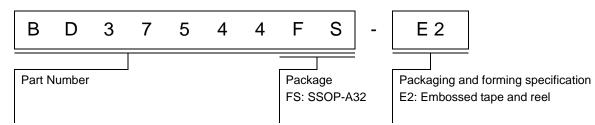
Short Pins 15 to 16, Pins 18 to 19 as shown in Figure 33 when the Super Bass function is not used.



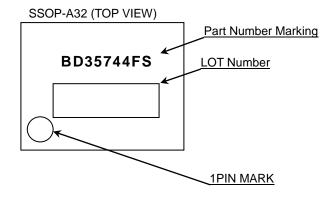
Short Pin 15 to 16, Pin 18 to 19

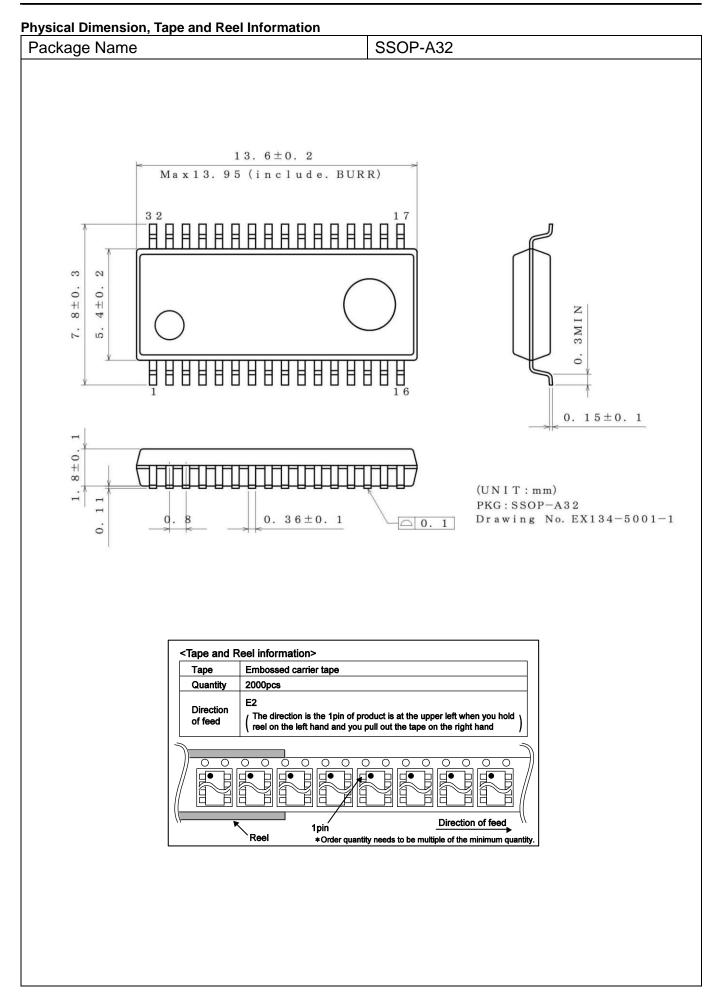
Figure 33. How to Deal with Pins of Super Bass when not used

## **Ordering Information**



## **Marking Diagram**





## **Revision History**

Date	Revision	Changes
16.Dec.2015	001	New Release

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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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